

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Prior Application: S. IMASU et al
 Serial No. 09/048,054
 Filed: March 26, 1998

Group Art Unit: 2841
 Examiner: J. Vigushin
 For: PROCESS FOR MOUNTING ELECTRONIC
 DEVICE AND SEMICONDUCTOR DEVICE

3/13
 3/6/01
 M. Fudgen

PRELIMINARY AMENDMENT

Assistant Commissioner of Patents
 Washington, D.C. 20231

Sir:

Prior to examination on the merits, please amend the
 above-identified application as follows:

IN THE SPECIFICATION:

Page 7, line 18, after "board)" insert --of the bump
 electrodes--.

Page 8, line 2, change "Fig. 4 is sections" to --Figs.

4(A), 4(B) and 4(C) are sectional views--.

Page 8, line 2, change "Fig. 4 is sections" to
 --Figs. 4(A), 4(B) and 4(C) are sectional views--;

line 25, change "B - B" to --II - II--.

Page 9, line 2, change "C - C" to --III - III--;

line 22, change "A - A" to --I - I--.

Page 22, line 18, after "(a section)." insert

--In this case also, as shown in Fig. 11, the passivation film
 5 is not formed between the semiconductor chip 10 and the soft
 layer 3.--

096944-012601

B'

Bd